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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of: Melvin K. CARTER

Confirmation No: 4809

Serial No: 10/689,616

Group: 1746

Filed: October 22, 2003

Examiner: S. Carrillo

Entitled: **COMPOSITION FOR EXFOLIATION  
AGENT EFFECTIVE IN REMOVING  
RESIST** Atty Docket: 60937-0141

**INFORMATION DISCLOSURE STATEMENT**

U.S. Patent and Trademark Office  
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Crystal Plaza, Lobby, Room 1B03  
Arlington, Virginia 22202

Sir:

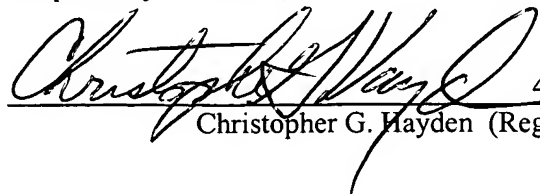
In accordance with the duty of disclosure provisions of 37 C.F.R. §1.56, there is hereby provided certain information which the Examiner may consider material to the examination of the subject U.S. patent application. It is requested that the Examiner make this information of record if it is deemed material to the examination of the application.

Enclosed with this Information Disclosure Statement is a list of all patents, publications, applications, or other information submitted for consideration by the Office. There are twenty-eight (28) references listed in the above-referenced application; no U.S. references are submitted, however, the three (3) foreign references, and seven (7) articles are submitted herewith. Remaining references can be provided upon request.

No fee is believed to be due for this submission, since this Information Disclosure Statement is being submitted before the first Office Action. Should any fees be required, however, please charge the required fees to Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310

Respectfully submitted,

Date December 16, 2004

  
44,750  
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**OTHER REFERENCES** *(Including Author, Title, Date, Pertinent Pages, Etc.)*

C01	Rafols, C. et al., J. Electroanalytic Chem., 433, pp. 77-83, 1997
C02	Ireland, P., Thin Solid Films, 304, pp. 1-12 (1997)
C03	K. Ueno et al., "Cleaning of CHF <sub>3</sub> Plasma-Etched SiO <sub>2</sub> /SiN/Cu Via Structures with Dilute Hydrofluoric Acid Solutions," J. Electrochem. Soc., vol. 144(7), 1997.
C04	Ohman et al., J. Chem. Soc., Dalton Trans. (1983), p. 2513).
C05	Kujime, T. et al., Proc. of the 1996 Semi. Pure Water and Chemicals, pp. 245-256,
C06	Baklanov, M.R. et al., Proc. Electrochem. Soc., 1998, 97-35, pp. 602-609.
C07	Lee, C. and Lee, S., Solid State Electronics, 4, pp. 92 1-923 (1997)
C08	NSF/SRC Eng. Res. Center, Environmentally Benign Semiconductor Manufacturing, Aug. 5-7, 1998, Stanford University. (no publication)
C09	

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



**LIST OF REFERENCES CITED BY APPLICANT**  
(Use several sheets if necessary)

ATTY DOCKET NO.

060937-0141-US

APPLICATION NO

10/689,616

APPLICANT

Melvin K. CARTER

FILING DATE

October 22, 2003

GROUP

1746

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	A01	3,592,773	03/1968	Muller			
	A02	4,395,479	07/1983	Ward et al.			
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	A08	5,129,955	08/1992	Tanaka			
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	A12	5,560,857	10/1996	Sakon et al.			
	A13	5,603,849	02/1997	Li			
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							YES	NO
	B01	0662 705	07/1995	EPO				
	B02	WO 98 02794	01/1998	PCT				
	B03	9-197681	07/1997	Japan				
	B04							
	B05							